



High-performance Thermal Conductive Gel

Product Description

SF-GE35PL-35 thermal gel, with high thermal conductivity materials filling in silica gel, which has many good properties, for example, extremely low thermal resistance, easy compression and a good interface filling effect. In the process of use, it exhibits easier to extrusion, low thermal resistance, heat transfer quickly and so on. At the same time, its electrical performance is good, with inert reaction, so it has a long stability in use.

Features

- Easy to compression, No rebound stress, Not top the screen
- Good gap filling ability, low thermal resistance
- Less oil impregnate, long service life
- Resistance to high and low temperature



Applications

- Mobile CPU & capacitance resist ance groups
- Thermal conductivity filling all heat so urce tiny gaps
- LED lighting heat radiator

Storage and Shelf Life

- Store in original cartons at 23±5°C and 60%±10% relative humidity in order to obtain best performance, besides use these products within 15 months from date of manufacture



SPECIFICATION

Physical Properties	Unit	SF-GE35PL-35	Test Method
Color	/	Grey	Visual Inspection
Density	g/cm ³	3.11	ASTM D792
Thermal Conductivity	W/m.K	3.5	ASTM D5470 Modify
Breakdown voltage	KV/mm	4.1	ASTM D149
Thermal Conductivity	°C*in ² /W	0.42	ASTM D5470 Modify
Thermal Conductivity		0.83	
Thermal Conductivity		1.22	
Volume resistivity	Ω.cm	10 ¹³	GB/T
Thermo-gravimetric	%	<0.5	1410 150°C 24h
Oil off degree	%	<0.01	HG/T 2502-93 5201
Application Temperature	°C	-40~+150	—